

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Y. SHIMADA, et al.

Serial No: 10/521,470

Filed: January 18, 2005

Title: MULTILAYER WIRING BOARD, MANUFACTURING METHOD THEREOF; SEMICONDUCTOR DEVICE, AND WIRELESS ELECTRONIC DEVICE

Group: 2818

Examiner: Phuc T. DANG  
Confirmation No. : 2249

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 10, 2006

Sir:

In response to the Office Action mailed July 10, 2006, please amend the above-identified application as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.